

-	44	(glass adj1 (substrate or board)) and (vias or (through adj1 holes)) and filler and ((wir\$ or conductive) adj1 pattern)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/01/06 17:05
-	225	(glass adj1 (substrate or board)) and (vias or (through adj1 holes)) and filler	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/01/16 09:05
-	19	"5744285"	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/01/16 09:23
-	4	"6392356"	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/01/16 09:24
-	32	"5463191"	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/01/16 09:25
-	268	glass adj1 (substrate or board) and (vias or (through near holes)) and (display adj1 device) and driver	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/01/16 11:45
-	15	"5739463"	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/01/22 09:23

L Number	Hits	Search Text	DB	Time stamp
-	320	glass near (substrate or board) and (vias or (through near holes)) and filler	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/01/22 09:23
-	30	glass near (substrate or board) and (vias or (through near holes)) and filler and (display near device)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15:55
-	49	361/760 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15:55
-	8	("4574255"   "5502889"   "5854534"   "5953213"   "6052287"   "6137167"   "6333857"   "6362525").PN.	USPAT	2003/03/04 15:47
-	23	361/748 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15:55
-	2	5912654.URPN.	USPAT	2003/03/04 16:11
-	13	361/750 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15:55
-	11	361/751 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15:55
-	18	361/761 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15:55
-	7	361/765 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15:56
-	14	361/767 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15:56
-	6	361/768 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15:56
-	11	361/772 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15:56
-	219	glass near (substrate or board) and (vias or (through near holes)) and (display near device) and driver	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/01/16 11:44

-	103	gandhi near jayprakash and electromagnetic and (holes or apertures)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/11 11:43
-	38	glass near (substrate or board) and (vias or (through near holes)) and filler and (display near device)	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 16:13
-	52	361/760 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15:56
-	26	361/748 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15:57
-	15	361/750 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15:57
-	13	361/751 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15:57
-	16	361/761 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15:57
-	8	361/765 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15:57
-	19	361/767 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15:57
-	7	361/768 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15:57
-	10	361/772 and glass near (substrate or board) and (vias or (through near holes))	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/20 15:57
-	1	roehling.in. and eves.in.	EPO; JPO; DERWENT	2003/08/20 15:57
-	344	glass near (substrate or board) and (vias or (through near holes)) and filler	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2004/01/16 09:22

-	109	349/\$ and glass near (substrate or board) and (vias or (through near holes)) and (display near device) and driver	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/03/06 11:01
-	48	359/\$ and glass near (substrate or board) and (vias or (through near holes)) and (display near device) and driver	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/03/06 11:37
-	42	313/\$ and glass near (substrate or board) and (vias or (through near holes)) and (display near device) and driver	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/03/06 11:53
-	1	"5739634".PN.	USPAT	2003/03/06 12:00
-	4	5739634.URPN.	USPAT	2003/03/06 12:02
-	0	6275254.URPN.	USPAT	2003/03/06 12:13
-	5	("4164683"   "4410830"   "5541478"   "5736814"   "5739634").PN.	USPAT	2003/03/06 12:13
-	13	4164683.URPN.	USPAT	2003/03/06 12:14
-	4	5150005.URPN.	USPAT	2003/03/06 12:15
-	9	5644327.URPN.	USPAT	2003/03/06 12:36
-	4	(alkali near glass near (substrate or board)) and (vias or (through near holes)) and (display near device) and driver	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/03/06 12:52
-	19	445/\$ and glass near (substrate or board) and (vias or (through near holes)) and (display near device) and driver	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/03/06 12:59
-	4	5597518.URPN.	USPAT	2003/03/06 13:03
-	34	4577133.URPN.	USPAT	2003/03/06 13:06
-	26	levi near dameon	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/03/07 17:00
-	1	gandhi near jay	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/03/07 17:00
-	656	gandhi near jayprakash	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/11 11:42
-	1	roehling.in. and eves.in.	EPO; JPO; DERWENT	2003/08/20 15:57
-	0	2000236192.URPN.	USPAT	2003/08/11 11:23
-	1	roehling.in. and eves.in. and hewlett.as.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/08/20 15:56
-	166	gandhi near jayprakash and electromagnetic	USPAT; US-PGPUB; EPO; DERWENT; IBM_TDB	2003/08/11 11:43